

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings of claims in the application:

#### **Listing of Claims:**

Claims 1-9 (Canceled)

Claim 10 (Previously Presented): A method of mounting a semiconductor device on a mounting substrate, the method comprising:

providing the semiconductor device as including a semiconductor element, a sealing resin and a plurality of terminals,

the semiconductor element having a thickness of 200  $\mu\text{m}$  or less, a first surface wherein circuitry is formed, a second surface, and side surfaces positioned between the first and second surfaces, the sealing resin having a thickness equal to or greater than half a thickness of the semiconductor element so that the first surface is sealed by the sealing resin and the second and side surfaces are not sealed by the sealing resin, each of the plurality of terminals being electrically connected to the circuitry;

putting the semiconductor device on a mounting substrate, so that the first surface of the semiconductor device faces the mounting substrate; and

fixing the semiconductor device on the mounting substrate by a heat treatment.

Claim 11 (Previously Presented): The method according to claim 10, wherein the semiconductor element has a central portion and a peripheral portion surrounding the central portion, the peripheral portion having a step part, wherein a thickness of the sealing resin on the step part is greater than a thickness of the sealing resin on the central portion.

Claim 12 (Previously Presented): The method according to claim 10, wherein the mounting substrate is a printing board.

Claim 13 (Previously Presented): The method according to claim 11, wherein the mounting substrate is a printing board.

Claim 14 (Previously Presented): The method according to claim 10, wherein the plurality of terminals are solder balls, the heat treatment comprises reflow of the solder balls.

Claim 15 (Previously Presented): The method according to claim 11, wherein the plurality of terminals are solder balls, the heat treatment comprises reflow of the solder balls.

Claim 16 (Previously Presented): The method according to claim 12, wherein the

plurality of terminals are solder balls, the heat treatment comprises reflow of the solder balls.

Claim 17 (Previously Presented): The method according to claim 13, wherein the plurality of terminals are solder balls, the heat treatment comprises reflow of the solder balls.

Claim 18 (New): The method according to claim 10, wherein after said fixing, a gap exists between the semiconductor device and the mounting substrate, which are separated by the terminals.

Claim 19 (New): The method according to claim 10, wherein the thickness of the semiconductor element is larger than the thickness of the sealing resin.

Claim 20 (New): The method according to claim 19, wherein after said fixing, a gap exists between the semiconductor device and the mounting substrate, which are separated by the terminals.